

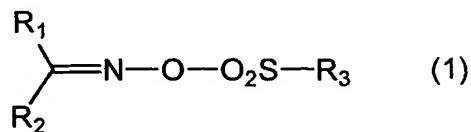
What is claimed is:

1. A positive photoresist composition comprising:

(A) an oxime sulfonate compound represented by the following formula (1),

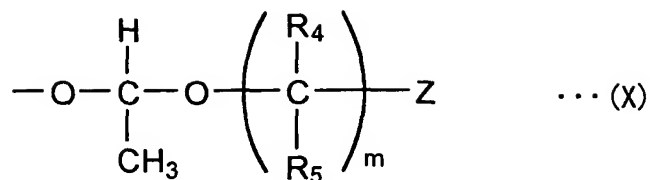
(B) a resin comprising repeating units including a group represented by the following formula (X) and which increases the solubility in an alkaline developing solution by the action of an acid, and

(C) a fluoroaliphatic-group-containing polymeric compound containing repeating units derived from a monomer represented by the following formula (2):

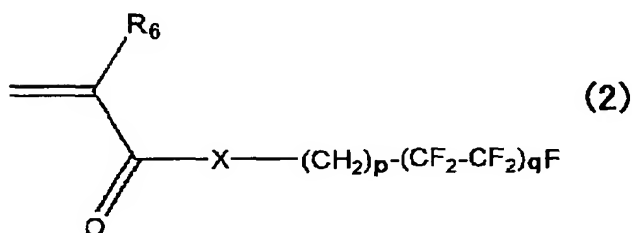


wherein R₁ and R₂ each independently represents an alkyl group, an alkenyl group, an alkynyl group, an aryl group, a heterocyclic group, or a cyano group, provided that R₁ and R₂ may be bonded to each other to form a ring, and R₃ represents an alkyl group or an aryl group, and

R₁ and R₂ each may be bonded, through a single bond or a connecting group, to the R₁ or R₂ of another compound represented by formula (1):

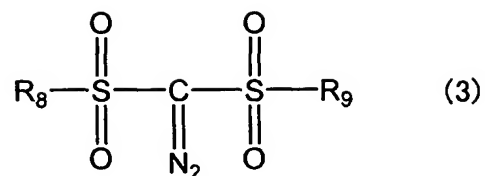


wherein R_4 and R_5 each independently represents a hydrogen atom or an alkyl group, Z represents an alkyl group, and m represents an integer of 1 to 20:



wherein R_6 represents a hydrogen atom or a methyl group, X represents an oxygen atom, a sulfur atom, or $-N(R_7)-$, p represents an integer of 1 to 6, and q represents an integer of 2 to 4, provided that R_7 represents a hydrogen atom or an alkyl group having 1 to 4 carbon atoms.

2. The composition according to claim 1, further comprising a compound represented by the following formula (3) which is capable of generating an acid upon irradiation with actinic rays or a radiation:



wherein R₈ and R₉ each independently represents an alkyl group or an aryl group.

3. The composition according to claim 1, wherein the amount of the compound represented by formula (1) is from 0.1 to 10% by weight based on the solid ingredients in the composition.

4. The composition according to claim 2, wherein the amount of the compound represented by formula (3) is from 0.01 to 7% by weight based on the solid ingredients in the composition.

5. The composition according to claim 2, wherein the proportion by weight of the compound represented by formula (1) to the compound represented by formula (3) is from 90/10 to 15/85.

6. The composition according to claim 1, wherein the content of the repeating units having a group represented by formula (X) is from 5 to 50% by mole based on all repeating units in the component (B).

7. The composition according to claim 1, further comprising an organic basic compound.

8. A method for forming a pattern, which comprises forming a resist film comprising the composition described in claim 1, exposing the resist film upon irradiation with the actinic rays or a radiation, and subsequently developing the resist film.